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Kind regards,

Team Nexperia

PDTA144V series

PNP resistor-equipped transistors; R1 = 47 k Ω , R2 = 10 k Ω

Rev. 04 — 3 September 2009

Product data sheet

1. Product profile

1.1 General description

PNP resistor-equipped transistors.

Table 1. Product overview

Type number	Package	Package		
	NXP	JEITA		
PDTA144VE	SOT416	SC-75	PDTC144VE	
PDTA144VK	SOT346	SC-59A	PDTC144VK	
PDTA144VM	SOT883	SC-101	PDTC144VM	
PDTA144VS[1]	SOT54	SC-43A	PDTC144VS	
PDTA144VT	SOT23	-	PDTC144VT	
PDTA144VU	SOT323	SC-70	PDTC144VU	

^[1] Also available in SOT54A and SOT54 variant packages (see Section 2)

1.2 Features

- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs

1.3 Applications

- General purpose switching and amplification
- Inverter and interface circuits

Circuit drivers

1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	-50	V
I _O	output current (DC)		-	-	-100	mA
R1	bias resistor 1 (input)		33	47	61	kΩ
R2/R1	bias resistor ratio		0.17	0.21	0.26	



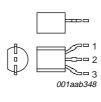
2. Pinning information

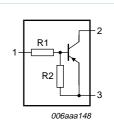
Table 3. Pinning

Pin	Description	Simplified outline Symbol
SOT54		
1	input (base)	
2	output (collector)	R1 L2
3	GND (emitter)	001aab347 R2 R2 006aaa148

SO	T5	4A

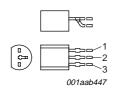
1	input (base)
2	output (collector)
3	GND (emitter)

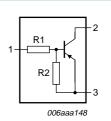




SOT54 variant

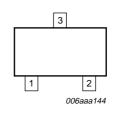
1	input (base)
2	output (collector)
3	GND (emitter)

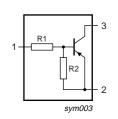




SOT23, SOT323, SOT346, SOT416

1	input (base)
2	GND (emitter)
3	output (collector)

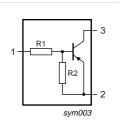




SOT883

1	input (base)
2	GND (emitter)
3	output (collector)





PDTA144V_SER_4

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3. Ordering information

Table 4. Ordering information

Type number	Package				
	Name	Description	Version		
PDTA144VE	SC-75	plastic surface mounted package; 3 leads	SOT416		
PDTA144VK	SC-59A	plastic surface mounted package; 3 leads	SOT346		
PDTA144VM	SC-101	leadless ultra small plastic package; 3 solder lands; body 1.0 \times 0.6 \times 0.5 mm	SOT883		
PDTA144VS[1]	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54		
PDTA144VT	-	plastic surface mounted package; 3 leads	SOT23		
PDTA144VU	SC-70	plastic surface mounted package; 3 leads	SOT323		

^[1] Also available in SOT54A and SOT54 variant packages (see Section 2 and Section 9).

4. Marking

Table 5. Marking codes

indicate in the second	
Type number	Marking code ^[1]
PDTA144VE	13
PDTA144VK	12
PDTA144VM	E9
PDTA144VS	TA144V
PDTA144VT	*AG
PDTA144VU	*12

^{[1] * = -:} made in Hong Kong

^{* =} p: made in Hong Kong

^{* =} t: made in Malaysia

^{* =} W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	-50	V
V_{CEO}	collector-emitter voltage	open base	-	-50	V
V_{EBO}	emitter-base voltage	open collector	-	–15	V
VI	input voltage				
	positive		-	+15	V
	negative		-	-40	V
I _O	output current (DC)		-	-100	mA
I _{CM}	peak collector current		-	-100	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 ^{\circ}C$			
	SOT416		<u>[1]</u> _	150	mW
	SOT346		<u>[1]</u> -	250	mW
	SOT883		[2][3]	250	mW
	SOT54		<u>[1]</u> -	500	mW
	SOT23		<u>[1]</u> -	250	mW
	SOT323		<u>[1]</u> -	200	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	ambient temperature		-65	+150	°C

^[1] Refer to standard mounting conditions.

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient	in free air				
	SOT416		<u>[1]</u> _	-	833	K/W
	SOT346		<u>[1]</u> _	-	500	K/W
	SOT883		[2][3]	-	500	K/W
	SOT54		<u>[1]</u> _	-	250	K/W
	SOT23		<u>[1]</u> _	-	500	K/W
	SOT323		<u>[1]</u> _	-	625	K/W

^[1] Refer to standard mounting conditions.

^[2] Reflow soldering is the only recommended soldering method.

^[3] Refer to SOT883 standard mounting conditions; FR4 printed-circuit board with 60 µm copper strip line.

^[2] Reflow soldering is the only recommended soldering method.

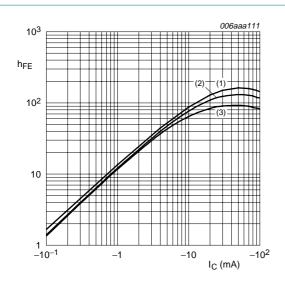
^[3] Refer to SOT883 standard mounting conditions; FR4 printed-circuit board with 60 µm copper strip line.

7. Characteristics

Table 8. Characteristics

T_{amb} = 25 °C unless otherwise specified

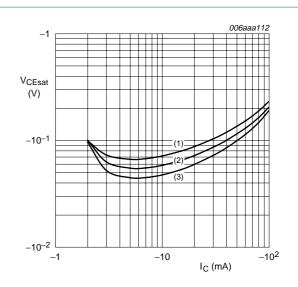
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I _{CBO}	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0 \text{ A}$	-	-	-100	nA
I _{CEO}	collector-emitter	$V_{CE} = -30 \text{ V}; I_B = 0 \text{ A}$	-	-	-1	μΑ
	cut-off current	$V_{CE} = -30 \text{ V}; I_{B} = 0 \text{ A};$ $T_{j} = 150 ^{\circ}\text{C}$	-	-	-50	μΑ
I _{EBO}	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_C = 0 \text{ A}$	-	-	-150	μΑ
h _{FE}	DC current gain	$V_{CE} = -5 \text{ V}; I_{C} = -5 \text{ mA}$	40	-	-	
V _{CEsat}	collector-emitter saturation voltage	$I_C = -10 \text{ mA}; I_B = -0.5 \text{ mA}$	-	-	-150	mV
$V_{I(off)}$	off-state input voltage	$V_{CE} = -5 \text{ V}; I_{C} = -100 \mu\text{A}$	-	-3.1	-1	V
$V_{I(on)}$	on-state input voltage	$V_{CE} = -300 \text{ mV}$; $I_{C} = -2 \text{ mA}$	-6	-3.8	-	V
R1	bias resistor 1 (input)		33	47	61	kΩ
R2/R1	bias resistor ratio		0.17	0.21	0.26	
C _c	collector capacitance	$V_{CB} = -10 \text{ V}; I_E = i_e = 0 \text{ A};$ f = 1 MHz	-	-	2	pF



$$V_{CE} = -5 \text{ V}$$

- (1) $T_{amb} = 100 \, ^{\circ}C$
- (2) $T_{amb} = 25 \,^{\circ}C$
- (3) $T_{amb} = -40 \, ^{\circ}C$

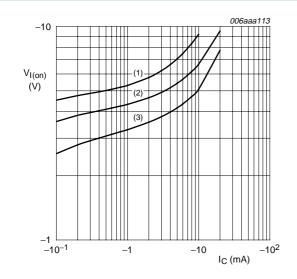
Fig 1. DC current gain as a function of collector current; typical values



$$I_{\rm C}/I_{\rm B} = 20$$

- (1) $T_{amb} = 100 \, ^{\circ}C$
- (2) $T_{amb} = 25 \, ^{\circ}C$
- (3) $T_{amb} = -40 \, ^{\circ}C$

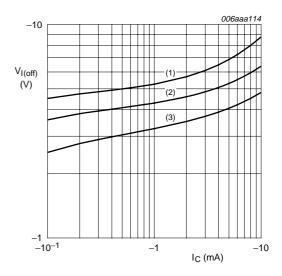
Fig 2. Collector-emitter saturation voltage as a function of collector current; typical values





- (1) $T_{amb} = -40 \, ^{\circ}C$
- (2) $T_{amb} = 25 \, ^{\circ}C$
- (3) $T_{amb} = 100 \, ^{\circ}C$

Fig 3. On-state input voltage as a function of collector current; typical values



$$V_{CE} = -5 \text{ V}$$

- (1) $T_{amb} = -40 \, ^{\circ}C$
- (2) $T_{amb} = 25 \, ^{\circ}C$
- (3) $T_{amb} = 100 \, ^{\circ}C$

Fig 4. Off-state input voltage as a function of collector current; typical values

8. Package outline

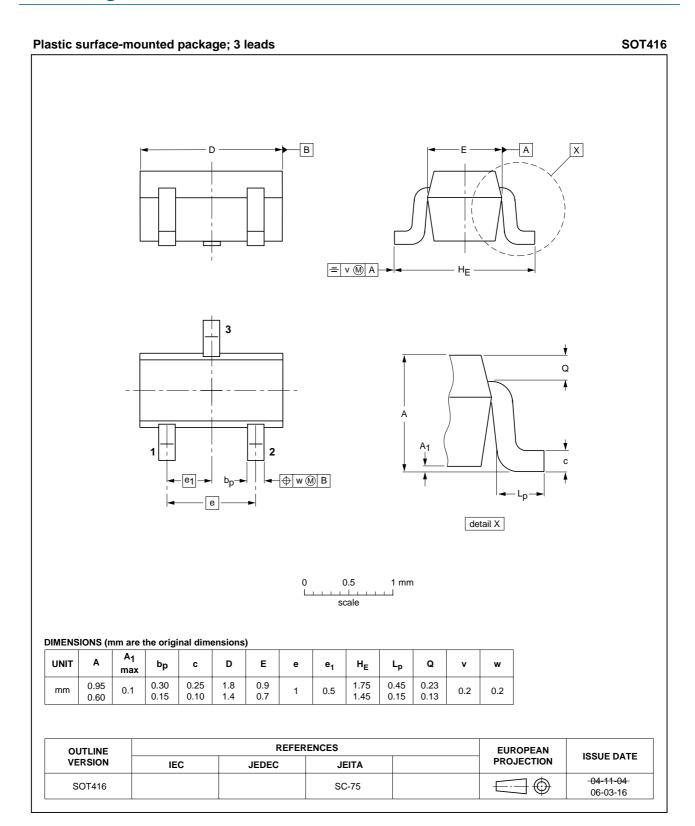


Fig 5. Package outline SOT416 (SC-75)

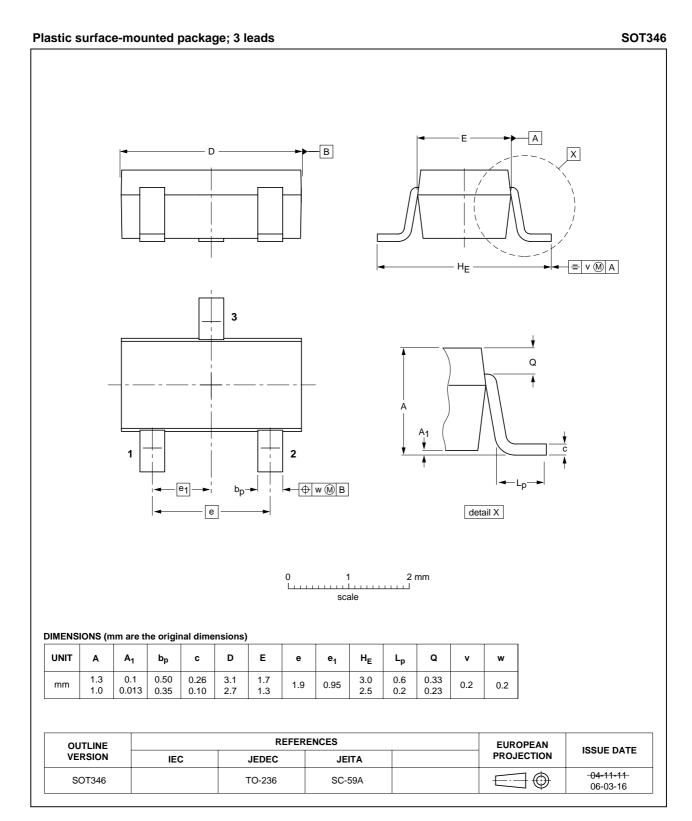


Fig 6. Package outline SOT346 (SC-59A/TO-236)

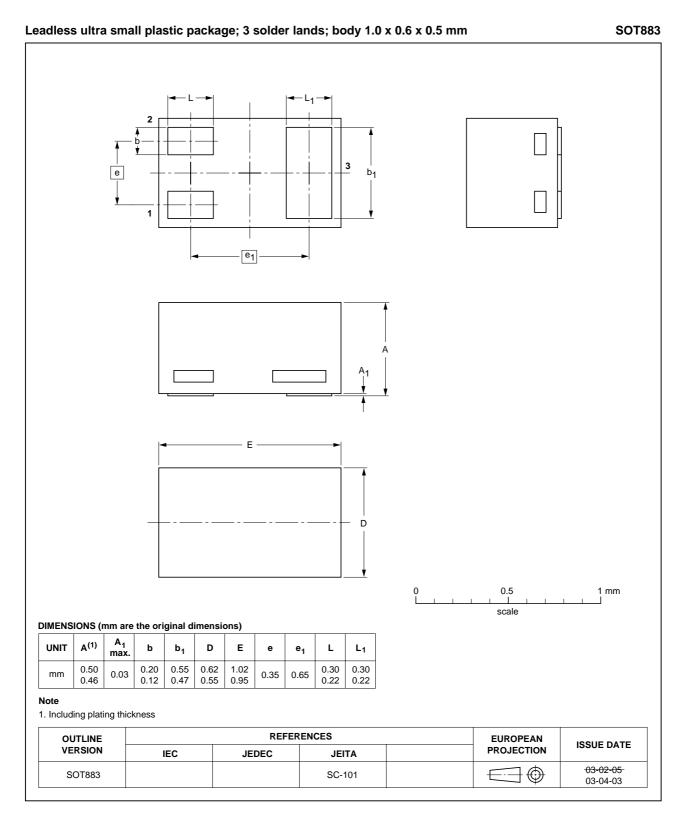
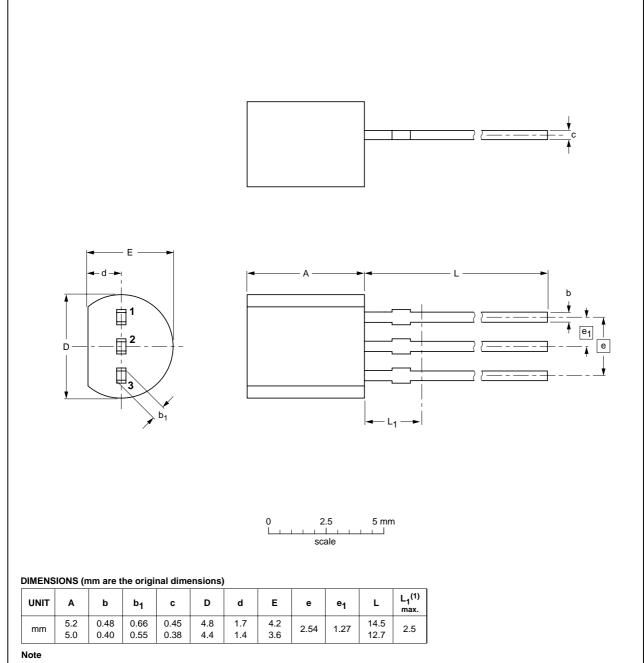


Fig 7. Package outline SOT883 (SC-101)

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE		REFERENCES EUROPEAN IS			ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT54		TO-92	SC-43A			-04-06-28- 04-11-16

Fig 8. Package outline SOT54 (SC-43A/TO-92)

Plastic single-ended leaded (through hole) package; 3 leads (wide pitch)

SOT54A

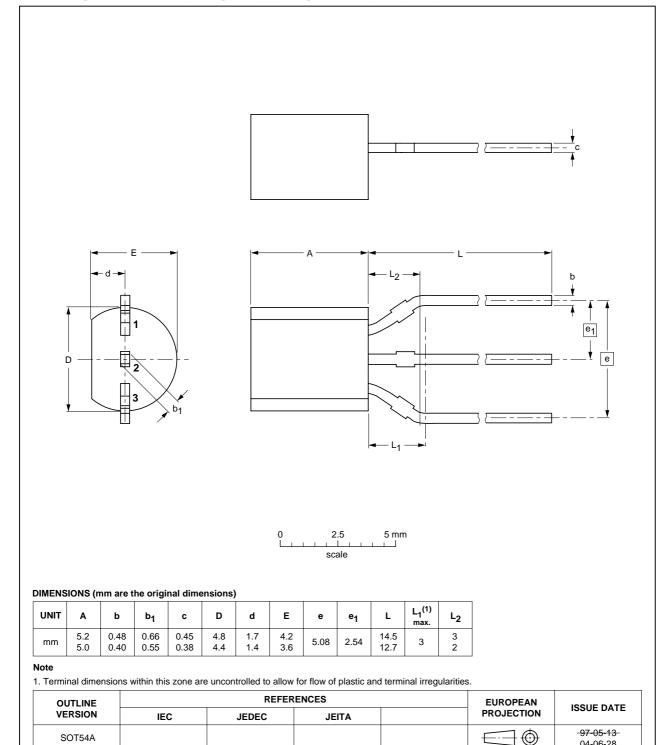


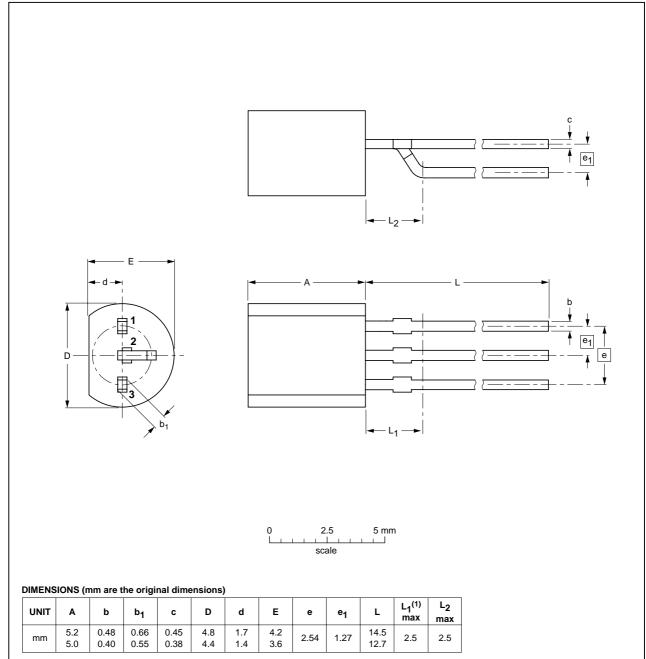
Fig 9. Package outline SOT54A

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04-06-28

Plastic single-ended leaded (through hole) package; 3 leads (on-circle)

SOT54 variant



Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT54 variant						-04-06-28 05-01-10

Fig 10. Package outline SOT54 variant

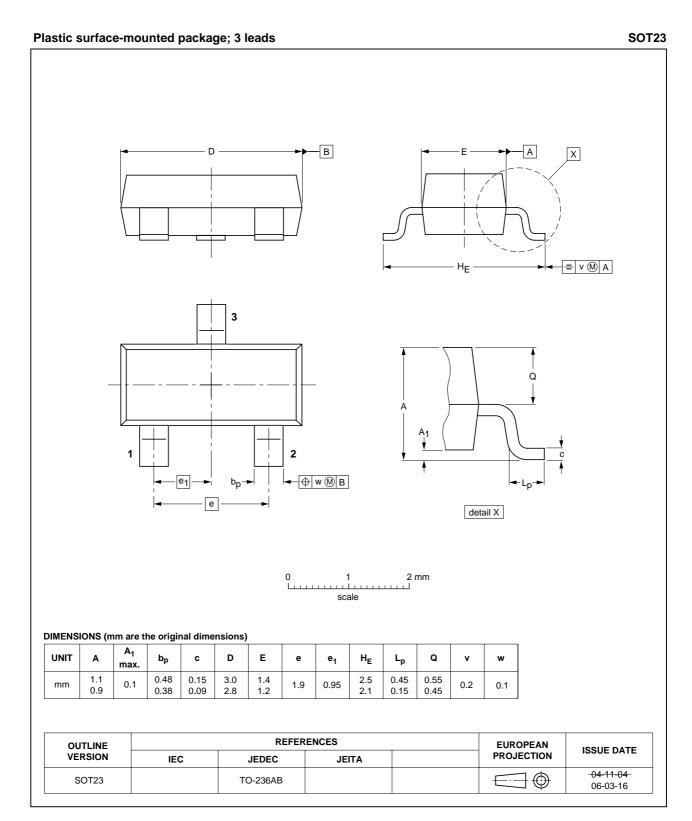


Fig 11. Package outline SOT23 (TO-236AB)

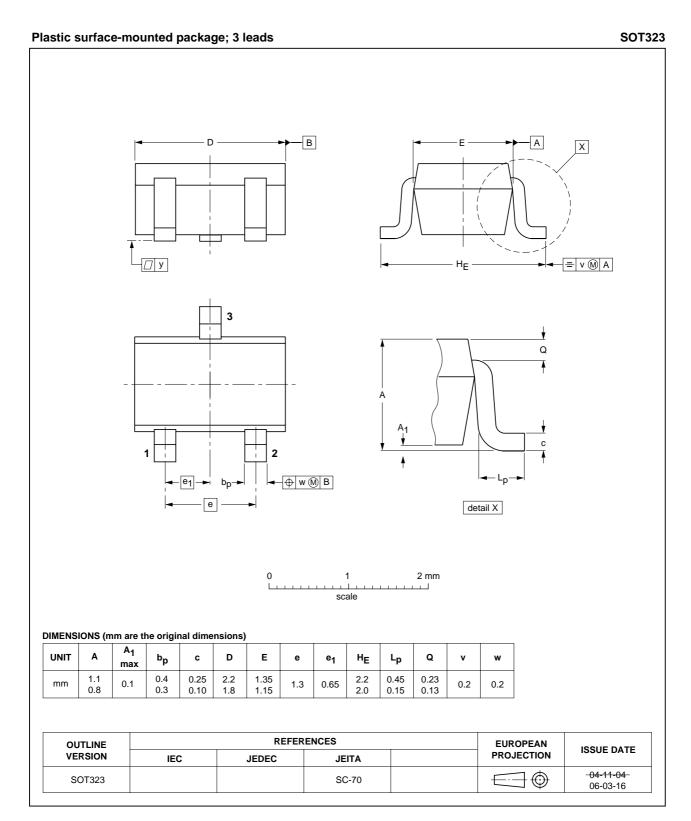


Fig 12. Package outline SOT323 (SC-70)

Packing information

Packing methods Table 9.

The indicated -xxx are the last three digits of the 12NC ordering code. [1]

Type number	Package	Description	Packing (Packing quantity		
			3000	5000	10000	
PDTA144VE	SOT416	4 mm pitch, 8 mm tape and reel	-115	-	-135	
PDTA144VK	SOT346	4 mm pitch, 8 mm tape and reel	-115	-	-135	
PDTA144VM	SOT883	2 mm pitch, 8 mm tape and reel	-	-	-315	
PDTA144VS	SOT54	bulk, straight leads	-	-412	-	
	SOT54A	tape and reel, wide pitch	•	-	-116	
		tape ammopack, wide patch	•	-	-126	
	SOT54 variant	bulk, delta pinning	-	-112	-	
PDTA144VT	SOT23	4 mm pitch, 8 mm tape and reel	-215	-	-235	
PDTA144VU	SOT323	4 mm pitch, 8 mm tape and reel	-115	-	-135	

^[1] For further information and the availability of packing methods, see Section 12.

10. Revision history

Table 10. Revision history

	•						
Document ID	Release date	Data sheet status	Change notice	Supersedes			
PDTA144V_SER_4	20090903	Product data sheet	-	PDTA144V_SER_3			
Modifications: • This data sheet was changed to reflect the new company including new legal definitions and disclaimers. No chang content				•			
	 Figure 5 "Package outline SOT416 (SC-75)":updated 						
 Figure 6 "Package outline SOT346 (SC-59A/TO-236)": updated 				ed			
	Figure 11 "F						
	 Figure 12 "Package outline SOT323 (SC-70)": updated 						
PDTA144V_SER_3	20050222	Product data sheet	-	PDTA144VT_2			
PDTA144VT_2	20040514	Objective data sheet	-	PDTA144VT_1			
PDTA144VT_1	20040305	Objective data sheet	-	-			

11. Legal information

11.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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